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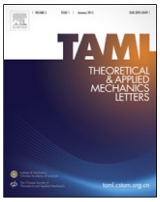

Letter

Adhesion-governed buckling of thin-film electronics on soft tissues

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HIGHLIGHTS

- Adhesion-governed buckling physics for thin-film on elastomer.
- The transitions between buckling modes are predicted analytically.
- Mechanics discussed in the context of bio-integrated electronics applications.

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ABSTRACT

Stretchable/flexible electronics has attracted great interest and attention due to its potentially broad applications in bio-compatible systems. One class of these ultra-thin electronic systems has found promising and important utilities in bio-integrated monitoring and therapeutic devices. These devices can conform to the surfaces of soft bio-tissues such as the epidermis, the epicardium, and the brain to provide portable healthcare functionalities. Upon contractions of the soft tissues, the electronics undergoes compression and buckles into various modes, depending on the stiffness of the tissue and the strength of the interfacial adhesion. These buckling modes result in different kinds of interfacial delamination and shapes of the deformed electronics, which are very important to the proper functioning of the bio-electronic devices. In this paper, detailed buckling mechanics of these thin-film electronics on elastomeric substrates is studied. The analytical results, validated by experiments, provide a very convenient tool for predicting peak strain in the electronics and the intactness of the interface under various conditions.

Stretchable electronics, being as stretchable and flexible as soft tissues, has enabled many important applications, such as [1–8] eyeball-like digital cameras [9,10], sensitive robotic skins [11,12], smart surgical gloves [13], comfortable skin sensor [14], and structural health monitoring devices [15]. Among these applications, some of the most important ones are the bio-integrated monitoring and therapeutic devices that can conform to the surfaces of soft bio-tissues such as the epidermis [16], the epicardium [17], and the brain [18], which provide promising options for long-term and portable healthcare devices. Upon contractions of the soft tissues, the electronics undergoes compression and buckles into various modes [19,20]. A few important mechanics models were developed to study the buckling problems on similar film-on-elastomer systems. Jiang et al. [2] studied the buckling behavior of strongly-bonded film-on-elastomer structures and predicted the maximum strain in the thin film to prevent fracture. Wang et al. [1] described local and global buckling modes for one-dimensional thin films or two-dimensional thin membranes on elastomers, and obtained the analytical critical conditions for separating the two buckling modes. Cheng et al. [21] introduced a bi-layer elastomeric substrate (a soft layer laminated on top of a relatively stiff one) that yields high levels of stretchability, and discussed the buckling and post-buckling behaviors. To achieve optimum bio-compatibility, Ko et al. [22] and Wang et al. [23] introduced advanced strategies to wrap thin-film electronics onto arbitrarily curvilinear shapes, for which Wang et al. [23] developed an analytical model to study the buckling patterns, and showed that the buckling behaviors are governed by the strength of the interface and the level of the compressive strain.

These important mechanics models indicate that the buckling behavior of these film-on-elastomer structures is related to the applied strain, the material and geometric parameters of the film, the stiffness of the elastomer, as well as the strength of the interfacial adhesion. In the context of bio-electronics applications where the tissues are the elastomeric substrate, *the stiffness of the tissues* and *the strength of the interface* can vary in a very wide range due to the type of tissues and changes in temperature, moisture, and bio-chemical activities. *The intactness of the interface* is of great importance to the functioning of electronic devices

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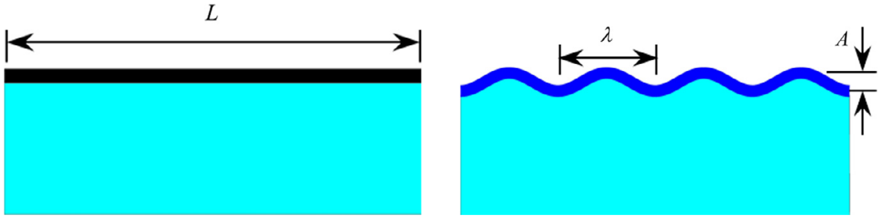
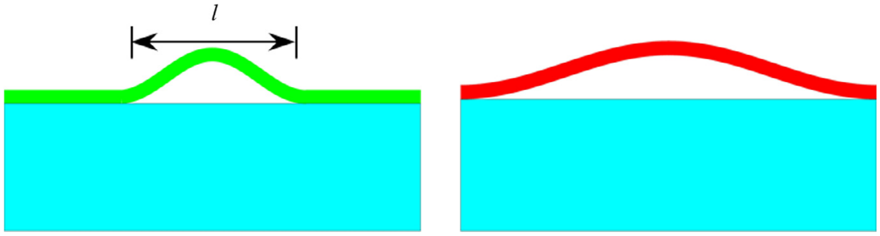


(a) Flat.

(b) Wrinkling.



(c) Partial delamination.

(d) Total delamination.

Fig. 1. The four buckling modes: (a) *flat*; (b) *wrinkling*; (c) *partial delamination*; (d) *total delamination*.

that rely on intimate contact and coupling to the tissues. Detailed mechanics analysis of the buckling physics that accounts for any tissue stiffness and any interfacial adhesion is presented in this study to predict the intactness of the bio-electronics interfaces.

The various buckling modes in the previous work [1,2,16–20] can be categorized into the four modes shown in Fig. 1. Under none to minor compression, the film does not buckle and remains *flat* (Fig. 1(a)); as the compression increases, the film wrinkles into multiple small waves on top of the elastomer but does not delaminate from the interface, which we refer to as the *wrinkling* mode (Fig. 1(b)); under further compression, the multiple waves merge into one and cause the film to partially delaminate from the interface, which is the *partial delamination* mode (Fig. 1(c)); more compression eventually causes the film to delaminate totally from the interface, which we define as the *total delamination* mode in this study (Fig. 1(d)). The energies of these different buckling modes are formulated and then compared in the next section to explain transitions between them.

Here we consider a film-structure of length L, thickness h, and Young's modulus E laminated on top of a soft substrate of Young's modulus E_{s}, and the work of adhesion for the interface is γ, and the structure is under a compressive applied strain of $|\varepsilon|$. By assuming a sinusoidal buckling shape of wavelength $0 < l < L$ (Fig. 1(c)), Wang et al. [23] analyzed the energies for the *flat, partial* and *total delamination* modes. Their analysis is elaborated in the Supplementary Information and summarized in the following. All the energies are normalized by $ELh\varepsilon_{\mathrm{c}}^2$ for convenience, where $\varepsilon_{\mathrm{c}} = \left(\pi^2 h^2\right) / \left(3L^2\right)$. We also define the following non-dimensional quantities: the normalized applied strain $e = |\varepsilon| / \varepsilon_{\mathrm{c}}$, the normalized critical wrinkling strain $e_{\mathrm{w}} = (3E_{\mathrm{s}}/E)^{2/3} / (4\varepsilon_{\mathrm{c}})$, the normalized adhesion $g = \gamma / \left(8Eh\varepsilon_{\mathrm{c}}^2\right)$ and the normalized delaminated length $a = l/L$.

For the *flat* mode, the total energy of the system consists of the membrane energy of the film, and the adhesion energy of the entire interface, and is obtained as

$$U^{\mathrm{flat}} = \frac{1}{2}e^2 - 8g. \tag{1}$$

For the *partial delamination* mode, the total energy consists of the membrane and bending energy of the film and the adhesion energy of the un-delaminated part of the interface [length of $(L-l)$], and is obtained as

$$U^{\mathrm{part.delam}} = ea^{-2} - \frac{1}{2}a^{-4} - 8g\,(1-a)\,. \tag{2}$$

Energy minimization with respect to a requires the first derivative of Eq. (2) to be zero and the second derivative to be greater than zero, therefore a can be solved from

$$\begin{cases} 4ga^5 - ea^2 + 1 = 0, \\ \sqrt{3/\,(5e)} < a \le 1, \end{cases} \tag{3}$$

where $a \le 1$ is due to the constraint that $l \le L$.

For the *total delamination* mode, the energy consists of the membrane and bending energy of the film, and is obtained as

$$U^{\mathrm{tot.delam}} = e - \frac{1}{2}. \tag{4}$$

In this study, we find that a fourth buckling mode, i.e. the *wrinkling* mode, exists under certain conditions. Following similar approach of Jiang et al. [2], the energy of this mode consists of the membrane and bending energies of the film, the strain energy of the substrate, as well as the adhesion energy of the interface, and can be obtained analytically as

$$U^{\mathrm{wrinkle}} = e_{\mathrm{w}}\left(e - \frac{1}{2}e_{\mathrm{w}}\right) - 8g. \tag{5}$$

It should be noted that this energy only exists when the applied strain exceeds the critical buckling strain, namely $e > e_{\mathrm{w}}$.

Here we adopt a typical case of $e_{\mathrm{w}} = 4$ and $g = 3$ to facilitate the discussion. Figure 2 shows the four energy curves versus the normalized strain e. All the curves are obtained analytically from Eqs. (1) to (5), except for the case of local buckling (blue curve). It is clearly shown in Fig. 2 that for very small strain e, the flat mode has the lowest energy. As e increases, *wrinkling, partial delamination* and then *total delamination* modes become the lowest energy state in sequence. Intersections of the above energy curves are important because they indicate the transitions from one buckling mode to another. Depending on the values of e_{w} and g, there are 6 possible intersections between these curves, which are found below.